## MSKSEMI















**ESD** 

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# Broduct data sheet













- 1. BASE
- 2. EMITTER
- 3. COLLECTOR

TRANSISTOR (NPN)

## MMBT3904T-MS **FEATURES**

- Complementary to MMBT3906T
- Small Package

MARKING: 1N

## MAXIMUM RATINGS (T<sub>a</sub>=25℃ unless otherwise noted)

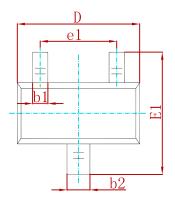
Symbol	Parameter	Value	Unit
V <sub>CBO</sub>	Collector-Base Voltage	60	V
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>EBO</sub>	Emitter-Base Voltage	6	V
Ic	Collector Current	200	mA
Pc	Collector Power Dissipation	150	mW
R <sub>OJA</sub>	Thermal Resistance From Junction To Ambient	833	°C/W
T <sub>J</sub> ,T <sub>stg</sub>	T <sub>J</sub> ,T <sub>stg</sub> Operation Junction and Storage Temperature Range		℃

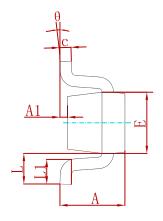
## **ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)**

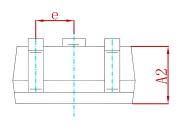
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =10μA, I <sub>E</sub> =0	60			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =1mA, I <sub>B</sub> =0	40			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =10μA, I <sub>C</sub> =0	6			V
Collector cut-off current	I <sub>CEX</sub>	V <sub>CE</sub> =30V, V <sub>EB(off)</sub> =3V			50	nA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =5V, I <sub>C</sub> =0			100	nA
	h <sub>FE(1)</sub>	V <sub>CE</sub> =1V, I <sub>C</sub> =0.1mA	40			
DC current acin	h <sub>FE(2)</sub>	V <sub>CE</sub> =1V, I <sub>C</sub> =1mA	70			
DC current gain	h <sub>FE(3)</sub>	V <sub>CE</sub> =1V, I <sub>C</sub> =10mA	100		300	
	h <sub>FE(4)</sub>	V <sub>CE</sub> =1V, I <sub>C</sub> =50mA	60			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =10mA, I <sub>B</sub> =1mA			0.2	V
Conector-entitler saturation voitage		I <sub>C</sub> =50mA, I <sub>B</sub> =5mA			0.3	V
Callagton amittan activistics valtage	V <sub>BE(sat)</sub>	I <sub>C</sub> =10mA, I <sub>B</sub> =1mA	0.65		0.85	V
Collector-emitter saturation voltage		I <sub>C</sub> =50mA, I <sub>B</sub> =5mA			0.95	V
Transition frequency	f⊤	V <sub>CE</sub> =20V,I <sub>C</sub> =10mA, f=100MHz	300			MHz
Collector output capacitance	C <sub>ob</sub>	V <sub>CB</sub> =5V, I <sub>E</sub> =0, f=1MHz			4	pF
Base input capacitance	C <sub>ib</sub>	V <sub>EB</sub> =0.5V, I <sub>C</sub> =0, f=1MHz			8	pF
Dalay time	t <sub>d</sub>	V <sub>CC</sub> =3V, V <sub>BE(off)</sub> =-0.5V I <sub>C</sub> =10mA,		25	ns	
Delay time		I <sub>B1</sub> =1mA		35		
Diag time	t <sub>r</sub>	V <sub>CC</sub> =3V, V <sub>BE(off)</sub> =-0.5V I <sub>C</sub> =10mA,			35	20
Rise time		I <sub>B1</sub> =1mA			30	ns
Storage time	ts	V <sub>CC</sub> =3V, I <sub>C</sub> =10mA, I <sub>B1</sub> = I <sub>B2</sub> =1mA			200	ns
Fall time	t <sub>f</sub>	V <sub>CC</sub> =3V, I <sub>C</sub> =10mA, I <sub>B1</sub> = I <sub>B2</sub> =1mA			50	ns



#### **PACKAGE MECHANICAL DATA**

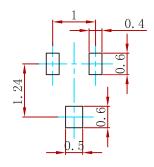






Comple ed	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	0.700	0.900	0.028	0.035	
A1	0.000	0.100	0.000	0.004	
A2	0.700	0.800	0.028	0.031	
b1	0.150	0.250	0.006	0.010	
b2	0.250	0.350	0.010	0.014	
С	0.100	0.200	0.004	0.008	
D	1.500	1.700	0.059	0.067	
Е	0.700	0.900	0.028	0.035	
E1	1.450	1.750	0.057	0.069	
е	0.500	TYP.	0.020	TYP.	
e1	0.900	1.100	0.035	0.043	
L	0.400	REF.	0.016	REF.	
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

## **Suggested Pad Layout**



#### Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

#### **REEL SPECIFICATION**

P/N	PKG	QTY
MMBT3904T-MS	SOT-523	3000



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